

**METHOD AND SYSTEM FOR HERMETICALLY SEALING
PACKAGES FOR OPTICS**

ABSTRACT OF THE DISCLOSURE

A method for hermetically sealing devices. The method includes providing a substrate which includes a plurality of individual chips. Each of the chips includes a plurality of devices and each of the chips are arranged in a spatial manner as a first array. The method also provides a transparent member of a predetermined thickness which includes a plurality of recessed regions arranged in a spatial manner as a second array and a standoff region. The method also includes aligning the transparent member in a manner to couple each of the plurality of recessed regions to a respective one of said plurality of chips. The method further includes hermetically sealing each of the chips within one of the respective recessed regions by using at least a bonding process to isolate each of the chips within one of the recessed regions.

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